



Professionally approved products

TECHNICAL DATA SHEET

RS 567-581 Epoxy Resin

RS 567-581 is a highly thixotropic, hot cure, one part epoxy resin system, designed for the discreet protection of electronic components by dipping or 'glob topping'.

- Fast cure at elevated temperatures
- High adhesion
- Excellent electrical properties
- High ionic purity
- Non toxic

Typical Properties

Usable Life	6 months @ 20°C (see storage conditions)
Cure Time	60 minutes @ 90°C 40 minutes @ 100°C 20 minutes @ 120°C
Specific Gravity	1.16
Ionisable Chlorine level	280 ppm
Shore D Hardness	~ 75
Water Absorption (3 hours in boiling water)	1%
Glass Transition Temperature	80°C
Dielectric Strength	12 kV/mm
Dielectric Constant (50Hz @ 20°C)	4.0

Storage

Store below 30°C. For extended usable life, store refrigerated. Allow to return to ambient temperature before use.